AAEON Technology INC.
ISO-9001/ISO-14001 Certified
Industrial Automation PCs

MB-668
Thermal Image Analysis Report

Release Date: JUNE.30, 2000

Issue Stamp	QA Manager	QE Manager	Test Engineer

Thermal Image Analysis

Ⅰ. **Model Name: PCM-668**

Ⅱ. **Description: Socket 370 LPX Board with LD, LAN, Audio, & 4 COMs**

Ⅲ. **Date: JUNE. 30, 2000**

Ⅳ. Measure **Site: AAEON QE Dept.**

Ⅴ. **Issued by : Fenglin Dong**

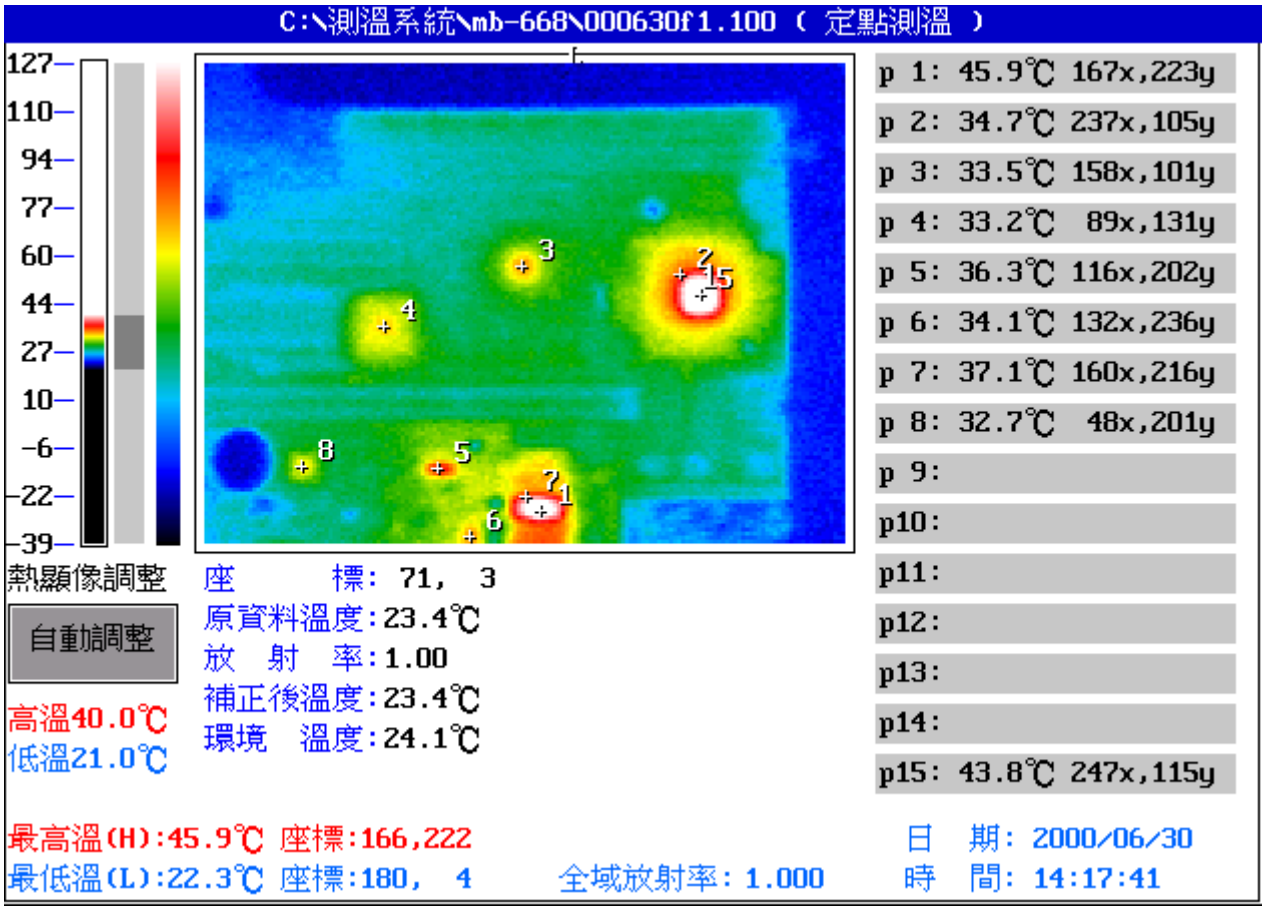
Ⅵ.**Equipment: TVS-100 series by NIPPON AVIONICS CO., LTD.**

Ⅶ. **Simulation Environment:**

- **Temperature: 25.2 degrees C**
- **CPU: Celeron**
- **RAM: 128 MB**
- **Hardware: DiskOnChip**
- **Application Software: QAPLUS/FE V5.2**
- **Take Picture Time: Power on 30 minutes after**

Ⅷ. Prediction Result:

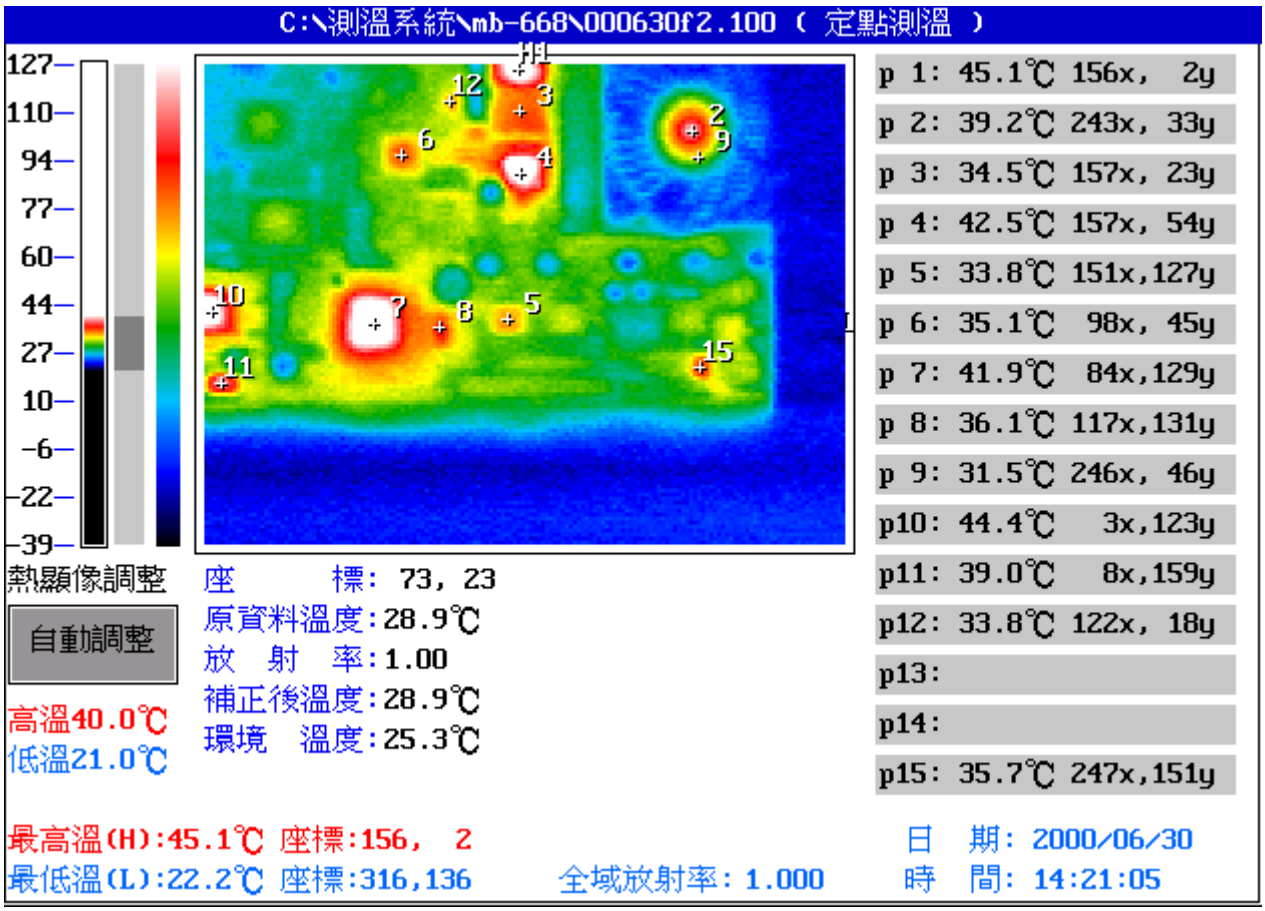
1. Component Side: 1/4



Point	Position	Describe	Ts	Tm	Note
1	U25	ICS, 9248-39	70	45.9	※ = -10.9
2	U10	INTEL,FW82443BX SL2VH	75	34.7	
3	U1			33.5	
4	U14			33.2	
5	U3	TI, 7407	75	36.3	
6	U36	ICS, ICS9112-16	70	34.1	
7	U25	ICS, 9248-39	70	37.1	※ = -2.1
8	U23			32.7	
9	---				
10	---				
11	---				
12	---				
13	---				
14	---				
15	U10			43.8	

1. Operation Temperature (℃):
   Ts = Defined by component specification ; Tm = Measured by QE
2. ※ = Ts - (Tm + 60 - 25)

Component Side: 2/4



Point	Position	Describe	Ts	Tm	Note
1	U25	ICS, 9248-39	70	45.1	※ = -10.1
2	CPU1	CPU		39.2	
3	---				
4	---				
5	---				
6	U37			35.1	
7	U12	CHIPS, B69000	70	41.9	※ = -6.9
8	U9			36.1	
9	CPU1			31.5	
10	U26	REALTEK, RTL8139B	70	44.4	※ = -9.4
11	Y5	EPSON, SG-8002JC50	70	39.0	※ = -4
12	U36			33.8	
13	---				
14	---				
15	U15			35.7	

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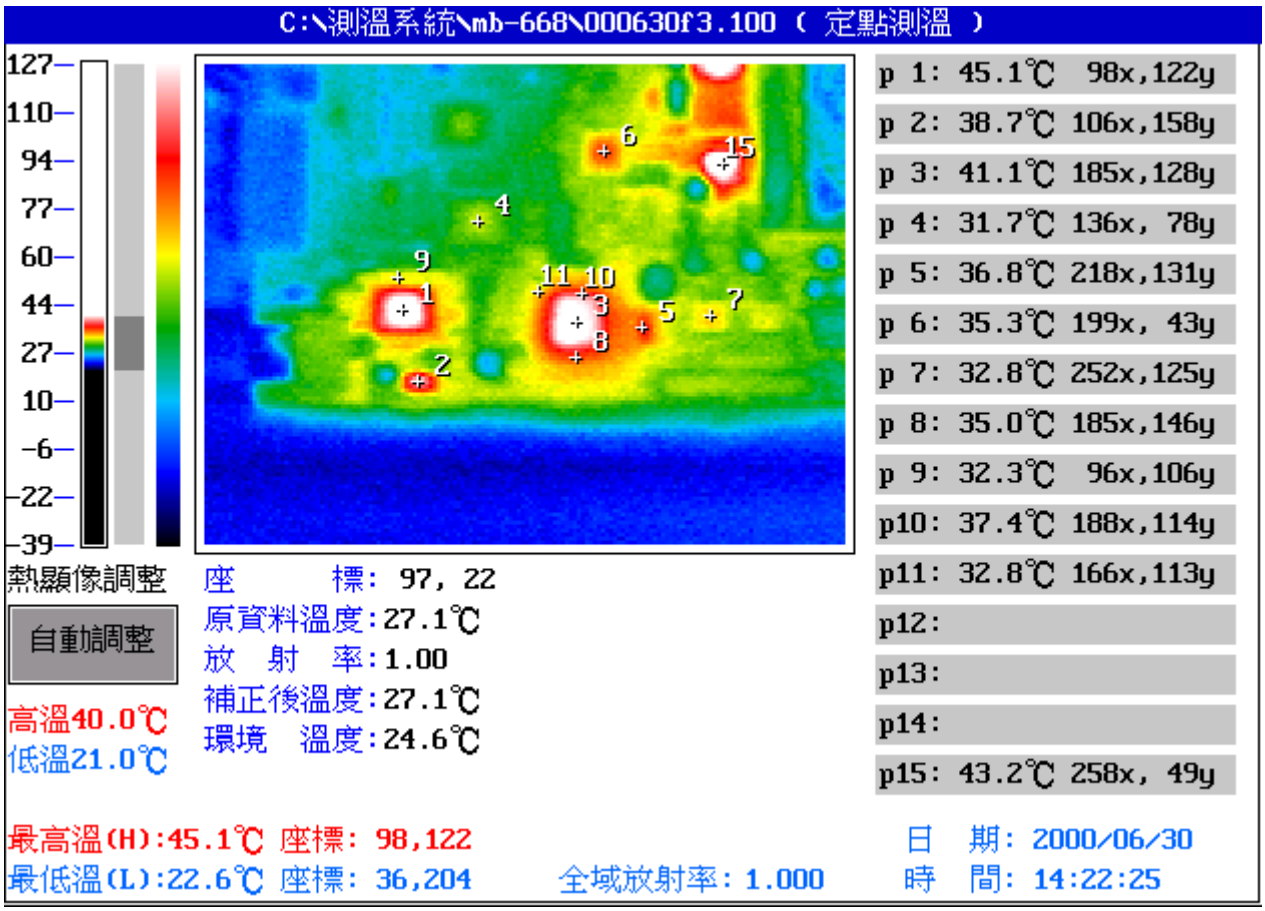
Component Side: 3/4



Point	Position	Describe	Ts	Tm	Note
1	U26	REALTEK, RTL8139B	70	45.1	※ = -10.1
2	Y5	EPSON, SG-8002JC50	70	38.7	
3	U12	CHIPS, B69000	70	41.1	※ = -6.1
4	U19			31.7	
5	U9			32.3	
6	U37	Aureal, AU8810-A2ACAA	70	35.3	
7	---				
8	U12			35.0	
9	U26			32.3	
10	U12	CHIPS, B69000	70	37.4	
11	U12	CHIPS, B69000	70	32.8	
12	---				
13	---				
14	---				
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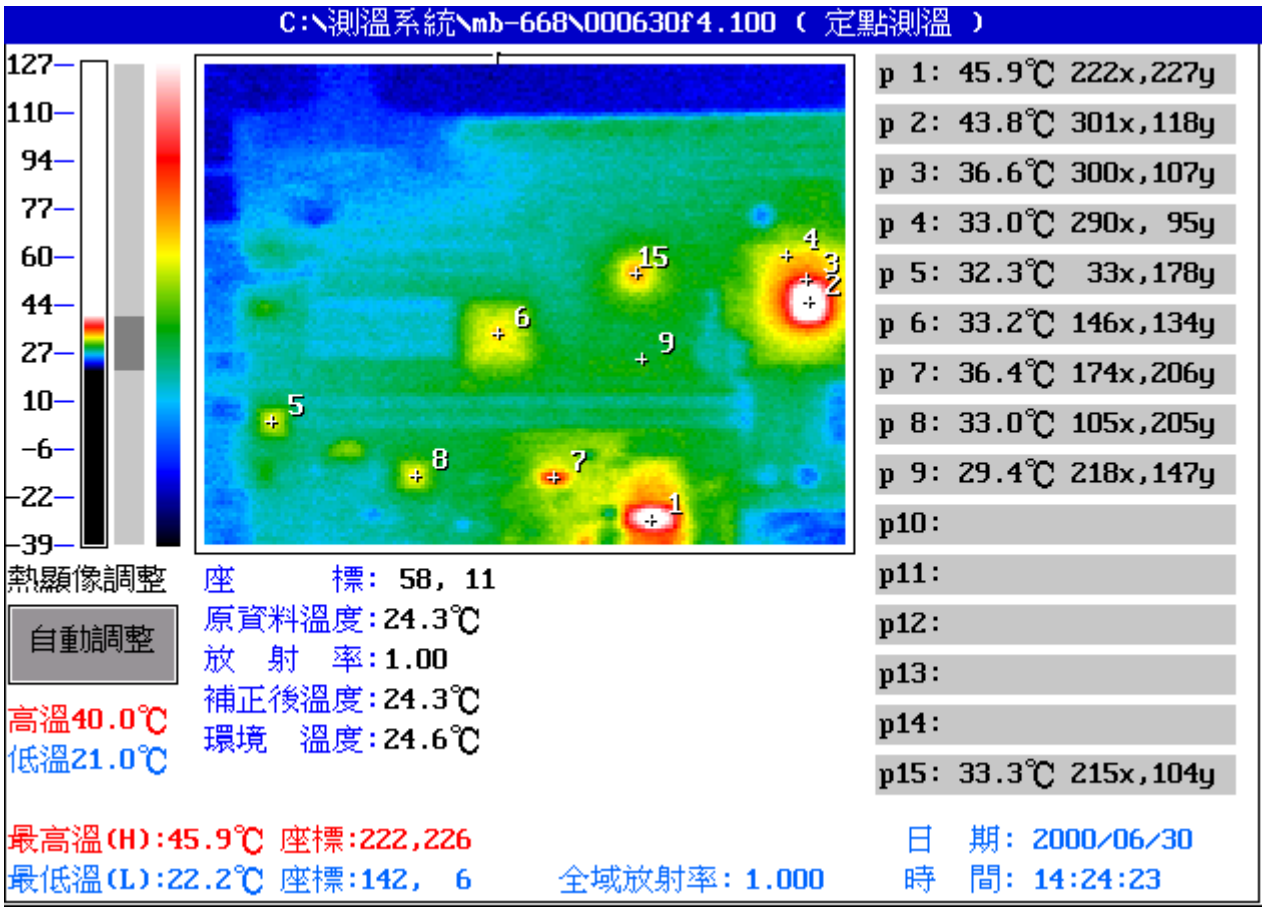
Component Side: 4/4



Point	Position	Describe	Ts	Tm	Note
1	U25	ICS, 9248-39	70	45.9	※ = -10.9
2	U10	INTEL, FW82443BX SL2VH	70	43.8	※ = -8.8
3	U10			36.6	
4	U10			33.0	
5	U38			32.3	
6	U14	TENYUN, 540-99-044-17-400	70	33.2	
7	U3	TI, 7407	75	36.4	
8	U23			33.0	
9	---			29.4	
10	---				
11	---				
12	---				
13	---				
14	---				
15	U1	INTEL, FW82371EB SL37M	70	33.3	

1. Operation Temperature (℃):
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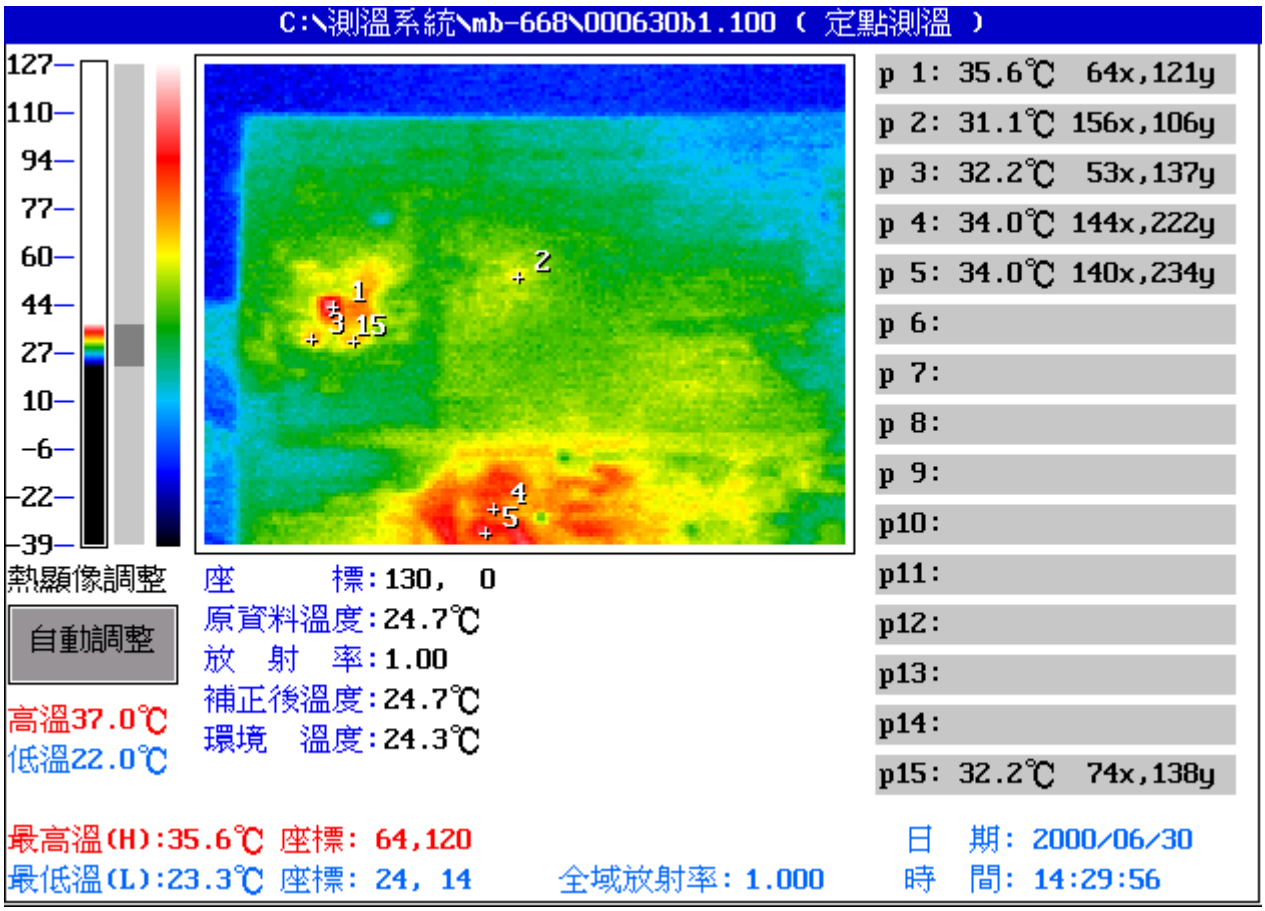
2. Solder Side: 1/4



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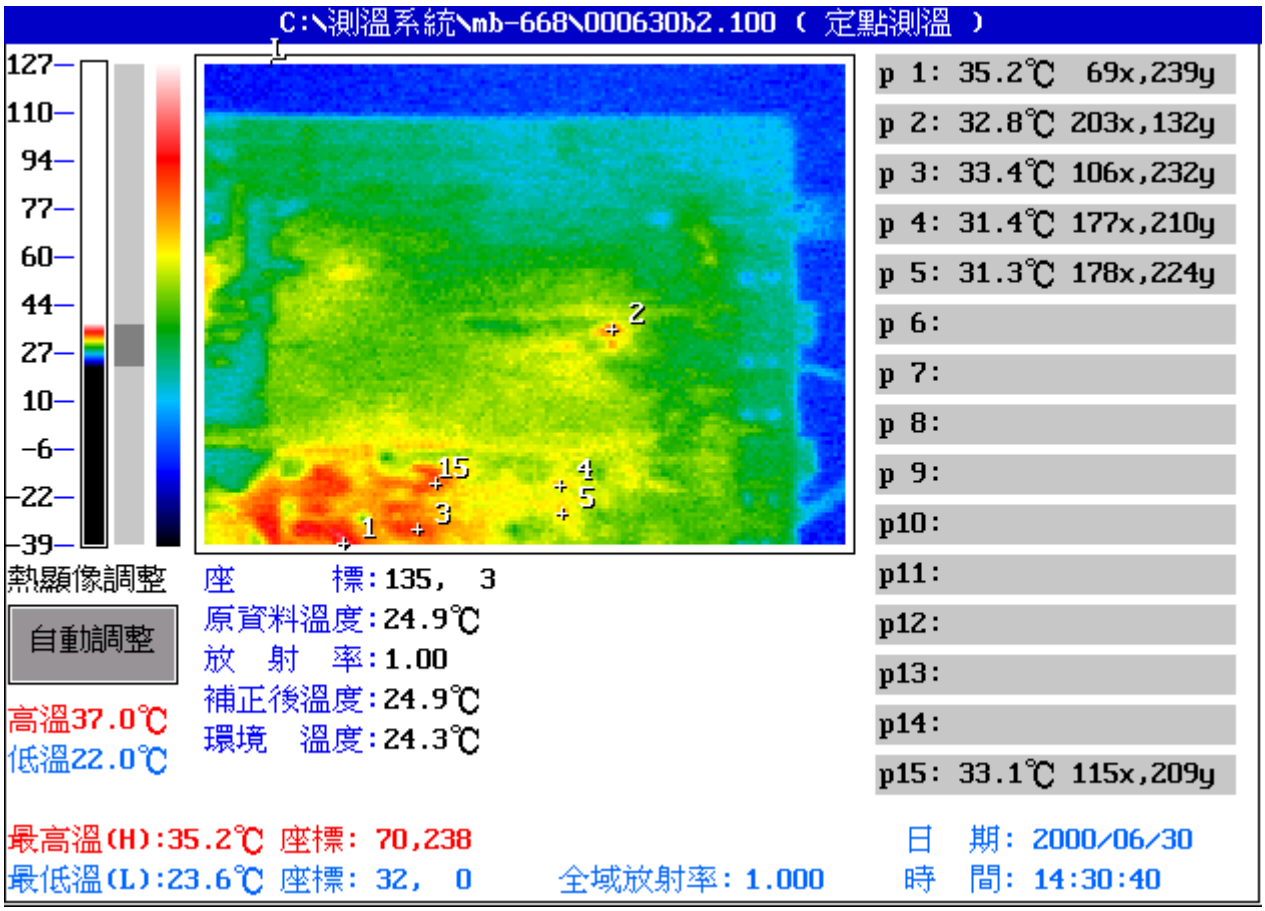
Solder Side: 2/4



Point	Position	Describe	Ts	Tm	Note
1	---				
2	---				
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4	---				
5	U16	TI, NE555		31.3	
6	---				
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14	---				
15	---				

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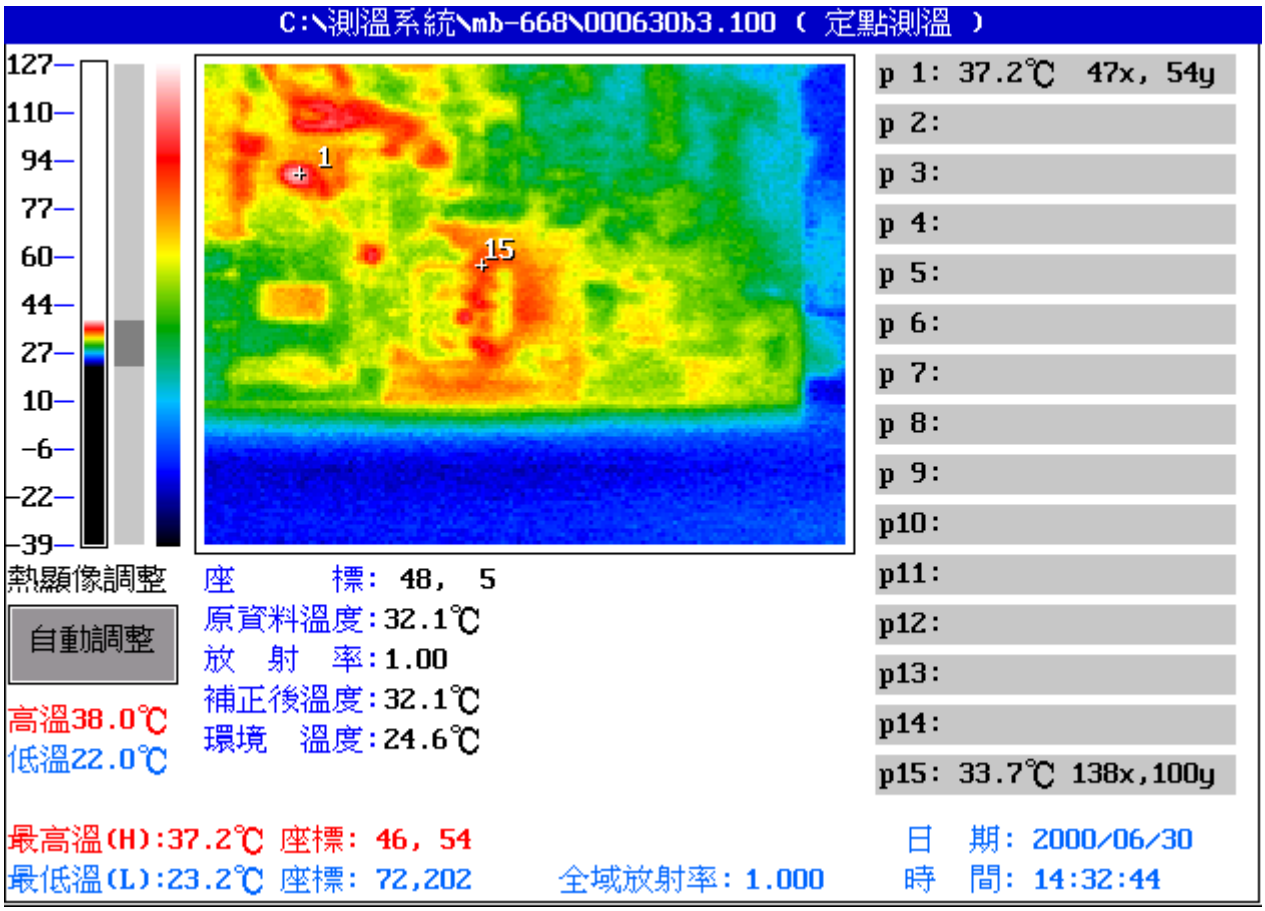
Solder Side: 3/4



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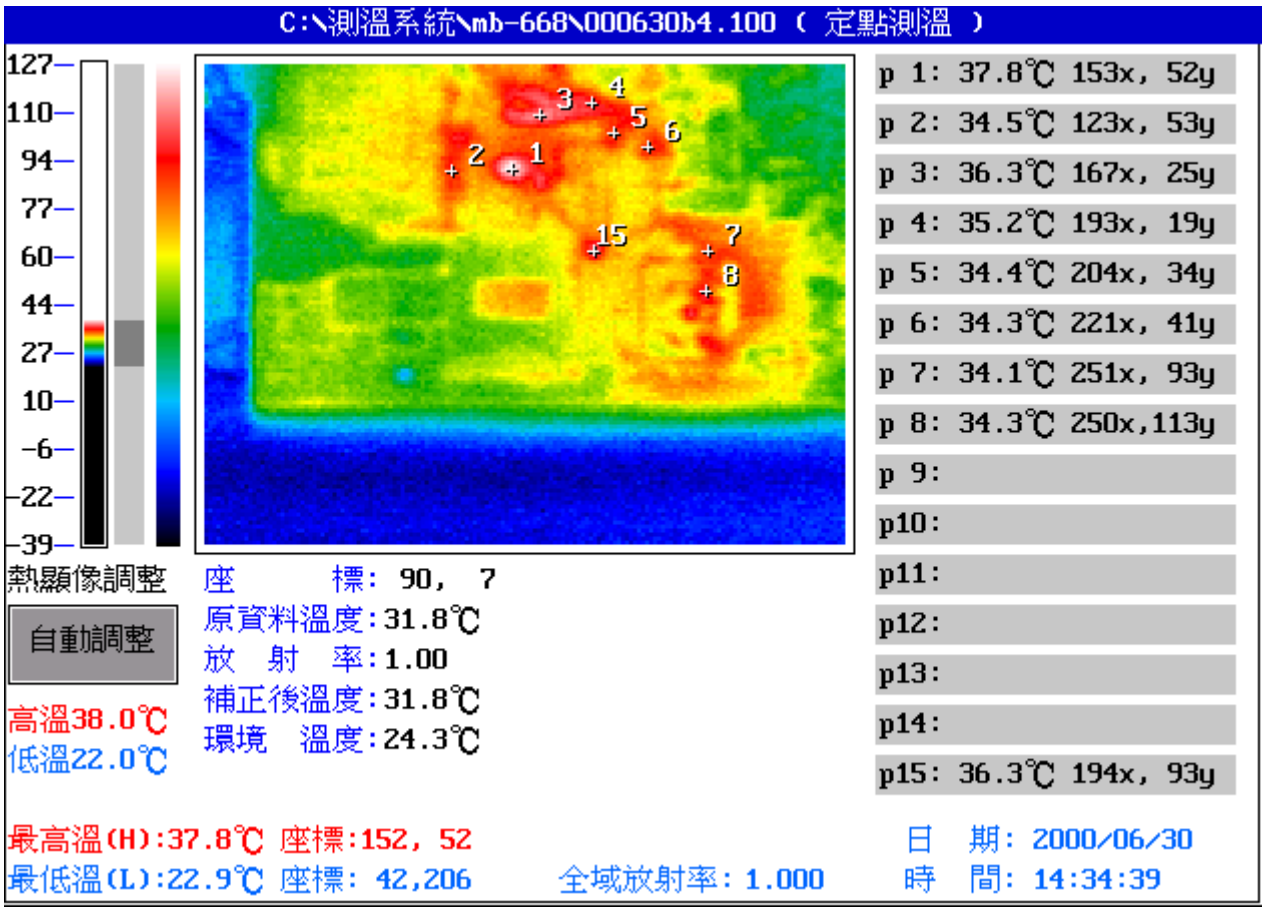
Solder Side: 4/4



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